

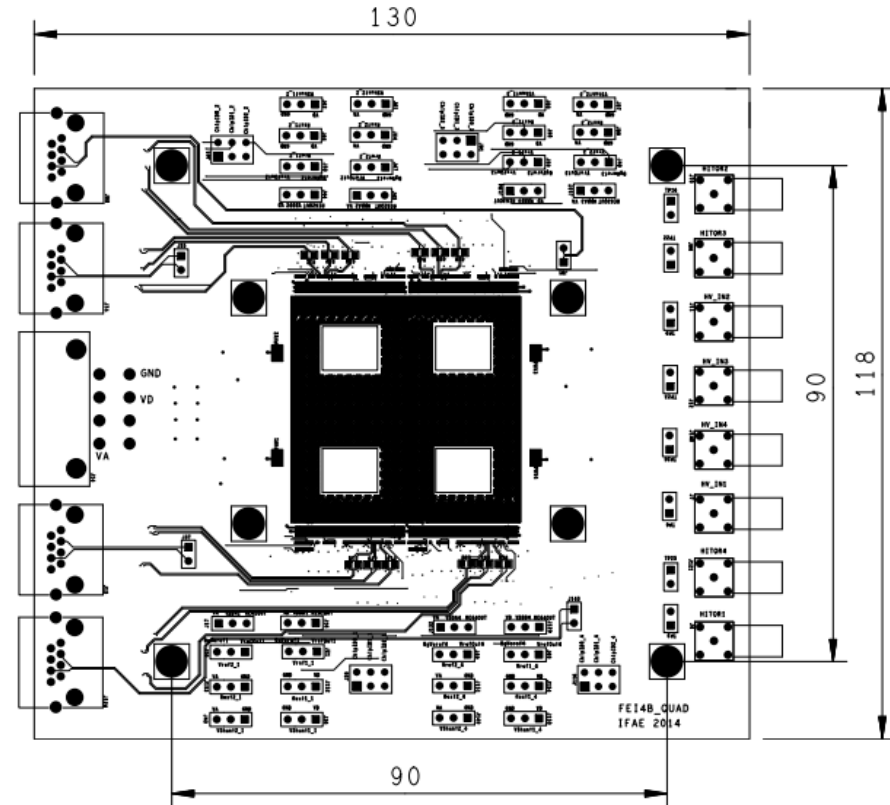
FEI4 Arm for AIDA Telescope

IFAE (Barcelona)

- Designed a PCB for FEI4 quad module
 - Inputs from Bonn and DESY
- Provide low quality 3D devices for testing

PCB for FEI4 quad module

- RJ45 connector for signals
- Single cmd/clk lines for 4 FE
- Power through regulator
- Each FE has a HitOr output
 - CMOS inverted
 - Will require extra PS on molex
- Holes compatible with existing single-chip card
- Four HV lemos for 4 single assembly prototype (use 1 if real QUAD)
- Expected dead area between single assemblies: 500um to 3mm (3mm along column, reduce by dicing?)



Carles Puigdengoles (IFAE)

➤ Design converging, expect to submit next week (~2 week production)

FEI4 quad 3D module prototype

- Plan to built 3D single chip QUAD with low quality IBL devices
- Flip-chip at IFAE
 - Left-overs form IBL (very low quality)
 - 700um thick FEI4B
 - So far only dummy tests
- Wire-bond to QUAD PCB
- Should be ready for June
- Also plan to mount with planar devices (Bonn), see other talks



IFAE



Expect to have PCBs fabricated mid April and mounted prototypes for June/July 2014

